

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L5	1744	"257"/\$.ccls. and mold with (protrus\$4 project\$4 opening cavit\$3) and (chip die ic) and (substrate board carrier) with (via hole opening)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/25 17:36
L6	248	"361"/\$.ccls. and mold with (protrus\$4 project\$4 opening cavit\$3) and (chip die ic) and (substrate board carrier) with (via hole opening)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/25 17:40
L7	741	"438"/\$.ccls. and mold with (protrus\$4 project\$4 opening cavit\$3) and (chip die ic) and (substrate board carrier) with (via hole opening)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/25 17:43
L8	336	"29"/\$.ccls. and mold with (protrus\$4 project\$4 opening cavit\$3) and (chip die ic) and (substrate board carrier) with (via hole opening)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/25 17:44